

Please replace the abstract with the following amended abstract:

The present invention provides a A semiconductor device comprising includes a die pad section $[(200)]$, a first semiconductor chip $[(4)]$ having a surface $[(41)]$ formed with a first electrode section $[(47)]$ and a back surface $[(42)]$ fixed to the die pad section $[(200)]$, a second semiconductor chip $[(5)]$ having a surface $[(51)]$ formed with a second electrode section $[(57)]$ and a back surface $[(52)]$ fixed to the surface $[(41)]$ of the first semiconductor chip $[(4)]$, a support member $[(300)]$ having a surface $[(301)]$ fixed to the back surface of the second semiconductor chip $[(5)]$ and a back surface $[(302)]$ fixed to the die pad section $[(200)]$, lead terminal sections $(210, 220)$ respectively electrically connected to the first and second electrode sections $(47, 57)$, and a resin encapsulating body $[(10)]$ that seals the die pad section $[(200)]$, the first and second semiconductor chips $(4, 5)$ and the support member $[(300)]$.